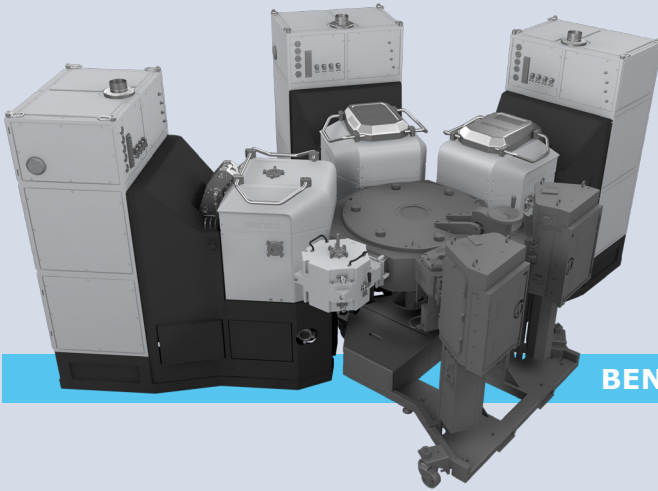


BENEQ TRANSFORM™



BENEQ TRANSFORM™

Versatile automated ALD platform for More-than-Moore device fabrication

- Combination of thermal and plasma ALD, single wafer or batch processing
- Ideal for oxide and nitride films in dielectrics, barrier, and passivation applications
- Optimized for metal films in electrode and contact applications
- Industry-standard horizontal wafer handling and automation, for seamless fab integration
- Proprietary wafer preheating option for maximum throughput; wafer pre-cleaning option
- Compact footprint and low cost-of-ownership

BENEQ TRANSFORM™

	TRANSFORM™	TRANSFORM™ LITE
MAXIMUM CONFIGURATION	3 ALD modules & 1 pre-heater	2 ALD modules & 1 pre-heater
PREHEATING CAPABILITY	Yes	Yes
TRANSFER MODULE	Brooks Mx600SS	Brooks Mx400
COOLING OPTION	Built-in	Facet-mounted
VCE LOADLOCKS	2	1
SUBSTRATE SIZE	3", 4", 6" or 8"	3", 4", 6" or 8"
SUBSTRATE	Si, GaN-on-Si, GaAs, InP, SiC, GaN, LNO, Sapphire	Si, GaN-on-Si, GaAs, InP, SiC, GaN, LNO, Sapphire
MAX. CONFIGURATION DIMENSIONS	3000x3000x2250 mm	3000x1250x2250 mm
INTEGRATION	SECS/ GEM	SECS/ GEM
THROUGHPUT AL2O3-200°C-50NM	40 wafers / hour	15 wafers / hour
THROUGHPUT HFO2-250°C-20NM	28 wafers / hour	13 wafers / hour